

# Device Characterization and Circuit Design Project Solutions

## 1 Characterization

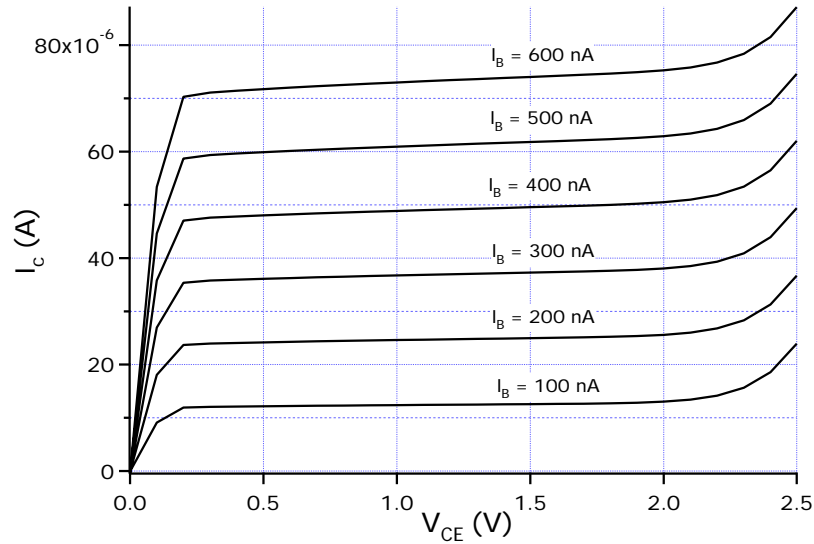


Figure 1: Graph 1

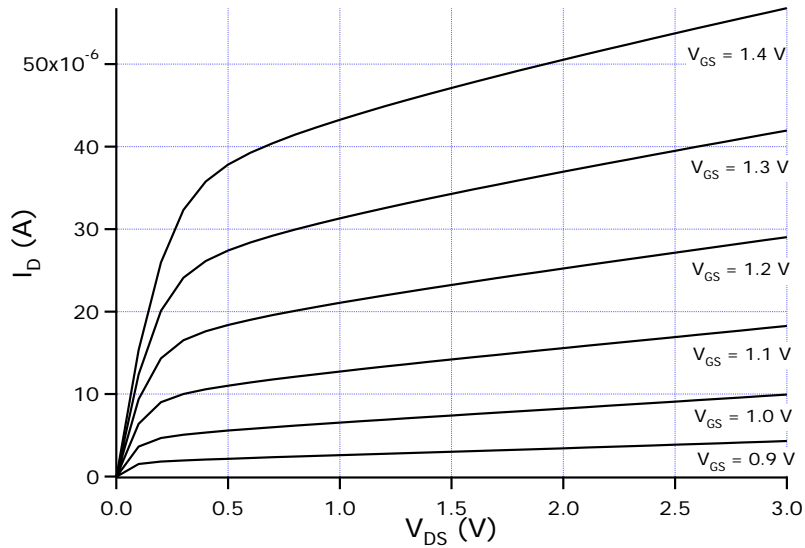


Figure 2: Graph 2

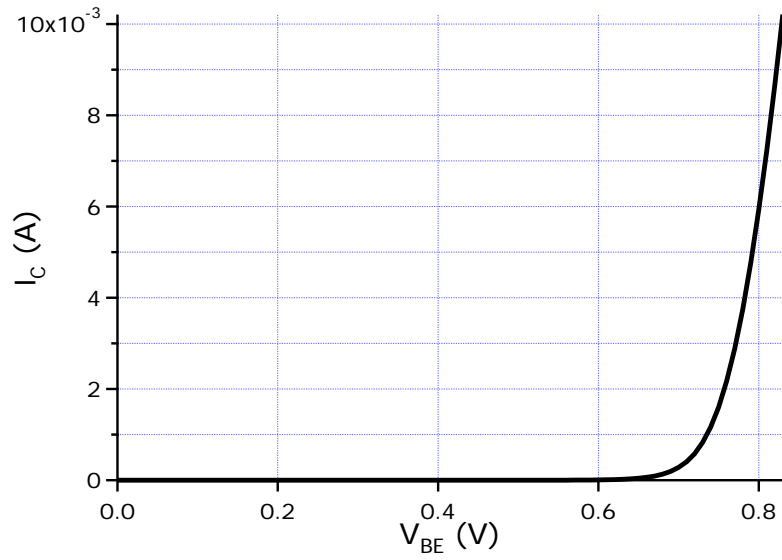


Figure 3: Graph 3

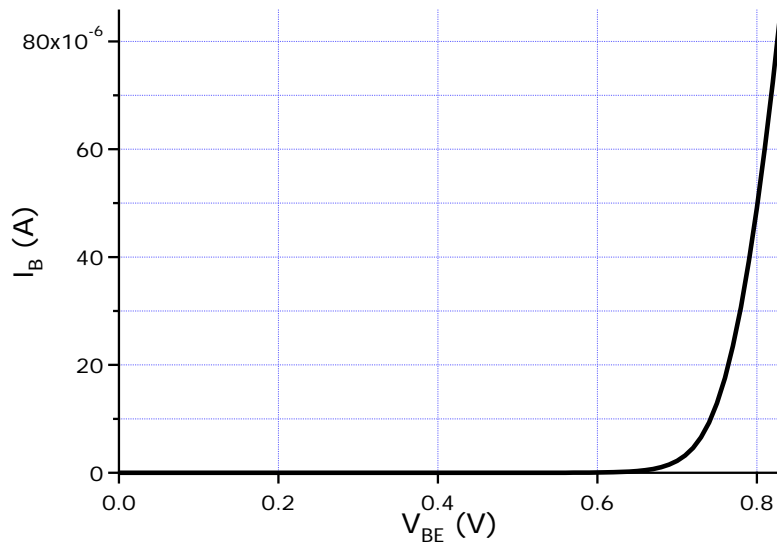


Figure 4: Graph 4

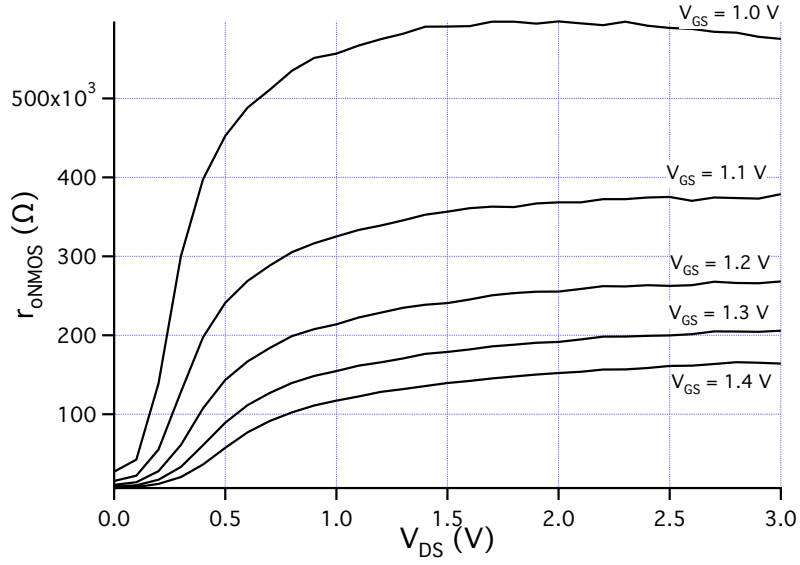


Figure 5: Graph 5

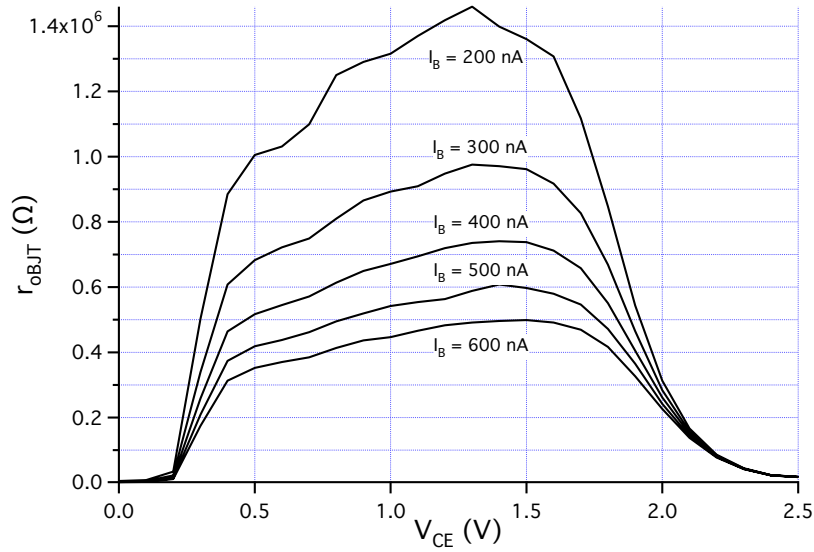


Figure 6: Graph 6

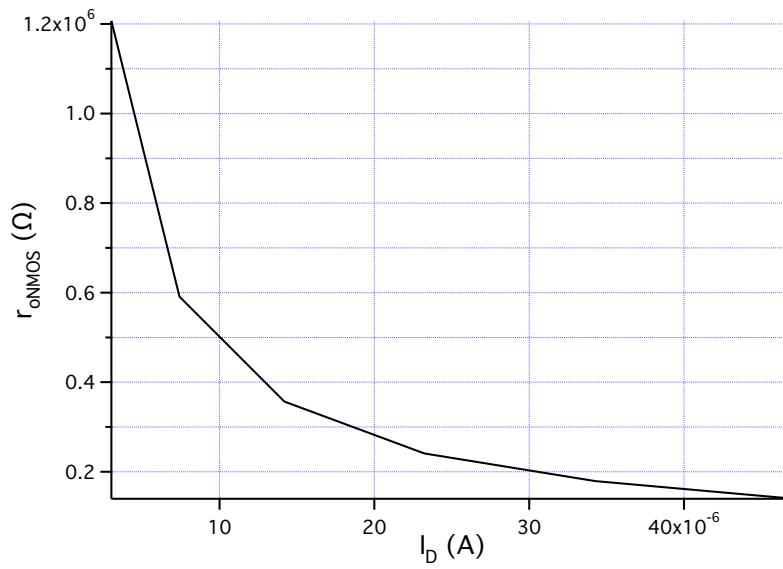


Figure 7: Graph 7

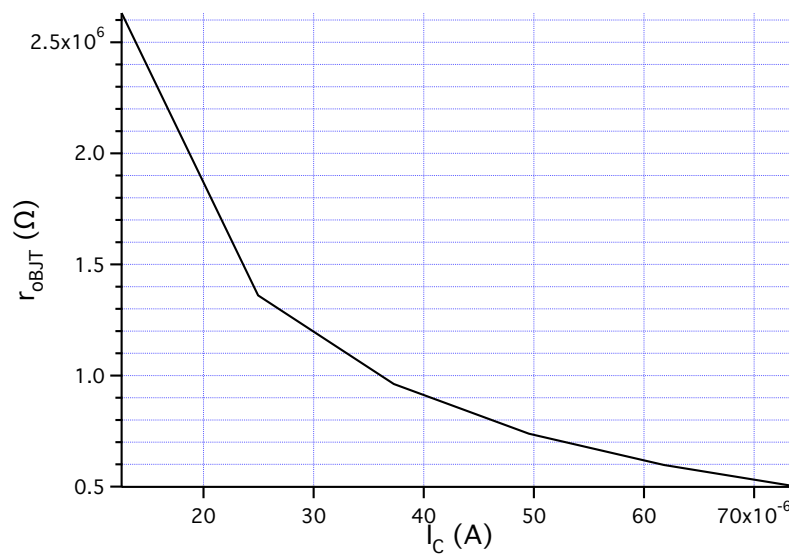


Figure 8: Graph 8



Figure 9: Graph 9

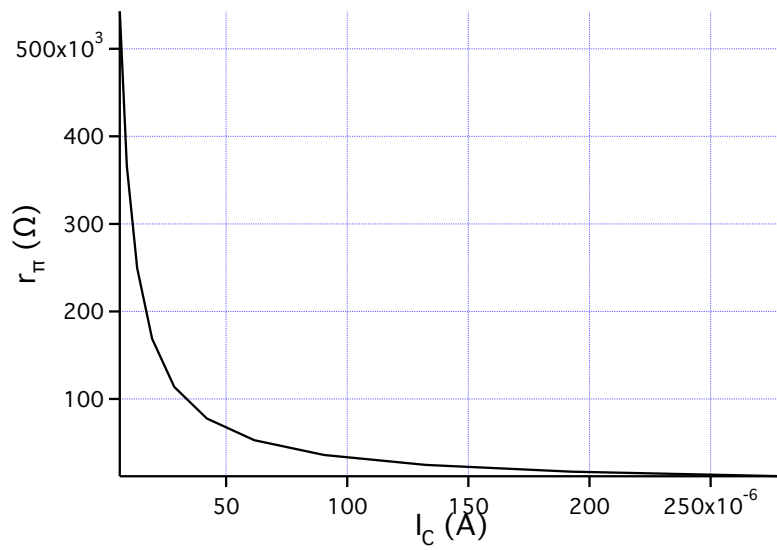


Figure 10: Graph 10

## 2 Amplifier Design (50 points total)

### 1. (Small Signal - 30 points)

To solve for the three parameters (gain, input resistance, output resistance), draw the small signal model and apply test voltages or currents, using KCL at the output (emitter) node.

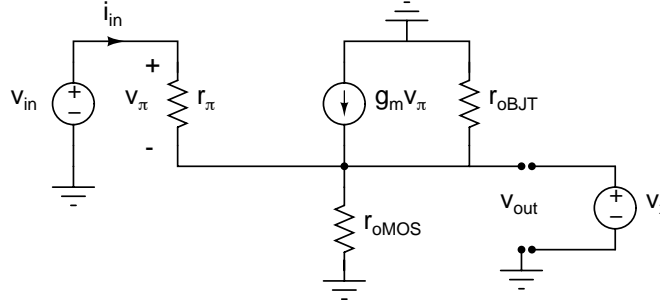


Figure 11: Small signal model of the amplifier. The n-MOSFET reduces to a transistor output resistance. The source  $v_x$  is attached to measure output resistance.

#### Gain:

$$\begin{aligned} \frac{v_{in} - v_{out}}{r_{\pi}} - \frac{v_{out}}{r_{oMOS}} - \frac{v_{out}}{r_{oBJT}} + g_m(v_{in} - v_{out}) &= 0 \\ v_{in}\left(g_m + \frac{1}{r_{\pi}}\right) &= v_{out}\left(\frac{1}{r_{\pi}} + \frac{1}{r_{oMOS} \parallel r_{oBJT}} + g_m\right) \\ \mathbf{A}_v &= \frac{1}{1 + \frac{r_{\pi}}{(\mathbf{g}_m r_{\pi} + 1)r_{oMOS} \parallel r_{oBJT}}} \end{aligned} \quad (1)$$

#### Input Resistance:

$$\begin{aligned} v_{in} &= i_{in}r_{\pi} + i_{in}(r_{oMOS} \parallel r_{oBJT}) + g_m i_{in}r_{\pi}(r_{oMOS} \parallel r_{oBJT}) \\ \mathbf{R}_{in} &= r_{\pi} + (\mathbf{g}_m r_{\pi} + 1)r_{oMOS} \parallel r_{oBJT} \approx \mathbf{g}_m r_{\pi}(r_{oNMOS} \parallel r_{oBJT}) \end{aligned} \quad (2)$$

#### Output Resistance:

$$\begin{aligned} i_x &= \frac{v_x}{r_{\pi}} + \frac{v_x}{r_{oMOS} \parallel r_{oBJT}} + g_m v_x \\ \mathbf{R}_{out} &= r_{oMOS} \parallel r_{oBJT} \parallel r_{\pi} \parallel \frac{1}{\mathbf{g}_m} \approx \frac{1}{\mathbf{g}_m} \end{aligned} \quad (3)$$

#### Range of bias current:

The lower limit of current is set by the output resistance specification. For  $R_{out} < 1000 \Omega$ , we require  $g_{mBJT} > 0.001$ . Solving the formula for  $g_m$  assuming room temperature provides an approximate value. For a more accurate result, consult Graph 9 for actual  $g_m$  vs.  $I_C$  data. This gives an answer  $\mathbf{I}_C > 28 \mu\mathbf{A}$ .

The upper limit is set by the input resistance or gain, whichever is the stricter specification. The gain spec was set to be quite loose at  $V_{OUT} = 1.5V$  but relatively strict at the swing endpoints. It is the input resistance specification that sets the high current limit. Intuitively, one can consider that  $r_\pi, r_{oMOS}$ , and  $r_{oBJT}$  are all inversely proportional to  $I_C$ , such that the factor in the denominator of the  $A_v$  expression should not change to first order with increasing current assuming that both transistors remain in their constant current regimes. The input resistance however depends on the factor  $g_m r_\pi = \beta$  which does not change with  $I_C$  to first order, and the output resistances of the transistors which do vary inversely with  $I_C$ . From the data in Graphs 7 and 8, we see that the output resistances remain high ( $> 15 k\Omega$ ) for  $I_D = I_C < 400 \mu A$ . The limiting factor is the MOSFET that eventually solidly enters its linear (low resistance) regime with increasing bias current. For  $I_D \approx 500 \mu A$ ,  $\beta \approx 100$ . Therefore we are looking for the point where  $r_{oMOS} \approx 10 k\Omega$ . This occurs for a current of about  $470 \mu A$ . However,  $V_{GS} = 3.3V$  is required to reach that current, so realistically the highest current that would be used is approximately  $440 \mu A$ , corresponding to  $V_{GS} = 3V$  (both answers are considered correct).

$$28 \mu A < I_C < 440 \mu A$$

2. (Bias point selection - 20 points)

The gain specification was set relatively low because of the wide swing that was required.

At the low swing ( $V_{CE} = 2.5 V$ ), the  $I_C$  of the BJT starts rising very quickly. The output resistance of the BJT thus becomes relatively very low at that point, independent of bias current. Additionally, as the bias current is raised (to lower  $r_\pi$ ), the mosfet starts to enter the linear region resulting in a lower output resistance for that device. It is a combination of those two effects that limit the swing towards the bottom rail and that limit the bias current.

At the high swing, we are limited by the BJT entering saturation ( $V_{CE} < V_{CEsat} \approx 0.2 V$ ).

The specs can be easily met with a current in the  $I_C = I_D = 25 - 60 \mu A$  range. As an example, consider  $I_C = 40 \mu A$ . From Graphs 2 and 3, this implies  $V_{GS} = 1.35V$ ,  $V_{BE} = 0.65V$ . Therefore, the bias voltages are  $V_B = 1.35 V$  and  $V_{BIAS} = 0.65 + 1.5 = 2.15 V$ .

Using Graphs 5-10, we extract all important values and calculate the specifications as shown in the following table.

|                      | $V_{OUT} = 1.5 V$ | $V_{OUT} = 0.5 V$ | $V_{OUT} = 2.5 V$ | Spec.     |
|----------------------|-------------------|-------------------|-------------------|-----------|
| $r_\pi (\Omega)$     | 77830             | 77830             | 77830             |           |
| $g_m (\Omega^{-1})$  | 0.00165           | 0.00165           | 0.00165           |           |
| $r_{oBJT} (\Omega)$  | 950k              | 18k               | 520k              |           |
| $r_{oNMOS} (\Omega)$ | 160k              | 57.5k             | 161k              |           |
| $A_v$                | 0.996             | 0.956             | 0.994             | $> 0.950$ |
| $R_{IN} (\Omega)$    | 18M               | 1.7M              | 15M               | $> 1M$    |
| $R_{OUT} (\Omega)$   | 606               | 606               | 606               | $< 1000$  |